



Complementary 30-V (D-S) MOSFET

PRODUCT SUMMARY						
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
P-Channel	- 30	0.051 at V _{GS} = - 10 V	- 6.4			
r-Ghannei		0.075 at V _{GS} = - 6 V	- 5.3			
N-Channel	30	0.035 at V _{GS} = 10 V	7.7			
		0.050 at V _{GS} = 4.5 V	6.5			

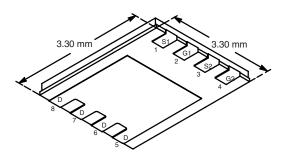
FEATURES

- · Halogen-free Option Available
- TrenchFET® Power MOSFET
- New Low Thermal Resistance
- PowerPAK[®] Package with Low 1.07 mm Profile



RoHS

PowerPAK 1212-8



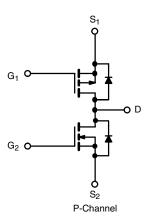
Bottom View

Ordering Information: Si7501DN-T1-E3 (Lead (Pb)-free)

Si7501DN-T1-GE3 (Lead (Pb)-free and Halogen-free)

APPLICATIONS

- · Backlight Inverter
- DC/DC Converter
 - 4 Cell Battery



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted								
			P-Channel		N-Channel			
Parameter		Symbol	10 s	Steady State	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	- 30		30		V	
Gate-Source Voltage		V_{GS}	± 25		± 20]	
Continuous Drain Current (T _{.I} = 150 °C) ^a	T _A = 25 °C	I _D	- 6.4	- 4.5	7.7	5.4	_	
Continuous Diain Curient (1) = 150 C)	T _A = 70 °C		- 5.1	- 3.6	4.7	4.3		
Pulsed Drain Current		I _{DM}	- 25		25		Α	
Continuous Source Current (Diode Conduction) ^a		I _S	- 2.6	- 1.3	2.6	1.3		
Marrian Darray Disaination	T _A = 25 °C	P _D	3.1	1.6	3.1	1.6	W	
Maximum Power Dissipation ^a	T _A = 70 °C		3	1.0	2	1.0		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150				°C	
Soldering Recommendations (Peak Temperature) ^{b, c}			260] [

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	t ≤ 10 s	- R _{thJA}	32	40		
Maximum Junction-to-Ambient ^a	Steady State		65	81	°C/W	
Maximum Junction-to-Foot (Case)	Steady State	R _{thJC}	5	6.3		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static		1						
Oaks Three should Walks as	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 1.0		- 3	V	
Gate Threshold Voltage		$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	1.0		3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$	P-Ch			± 200	nA	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch			± 100		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V	P-Ch			- 1		
		V _{DS} = 30 V, V _{GS} = 0 V	N-Ch			1	μΑ	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C	P-Ch			- 5		
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	N-Ch	N-Ch		5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	P-Ch - 25			† .	
		$V_{DS} \le 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	25			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 6.4 A	P-Ch		0.041	0.051	Ω	
		V _{GS} = 10 V, I _D = 7.7 A	N-Ch		0.028	0.035		
		V _{GS} = - 6 V, I _D = - 5.3 A	P-Ch		0.055	0.075		
		V _{GS} = 4.5 V, I _D = 6.5 A	N-Ch			0.050		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 6.4 A	P-Ch		13		S	
		V _{DS} = 15 V, I _D = 7.7 A	N-Ch		15			
	V _{SD}	I _S = - 1.7 A, V _{GS} = 0 V	P-Ch		- 0.80	- 1.2	.,	
Diode Forward Voltage ^a		I _S = 1.7 A, V _{GS} = 0 V	N-Ch		0.80	1.2	V	
Dynamic ^b	•				•			
Total Cata Charge	Qg		P-Ch		12.5	19		
Total Gate Charge		P-Channel $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6.4 \text{ A}$	N-Ch		9	14	nC	
Gate-Source Charge	Q _{gs}	V _{DS} = 10 V, V _{GS} = 10 V, I _D = 10.4 A	P-Ch		2.5			
		N-Channel	N-Ch		2			
Gate-Drain Charge		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 7.7 \text{ A}$	P-Ch		3.6			
			N-Ch P-Ch		1.3 9			
Gate Resistance	R_g		N-Ch		3		Ω	
	t _{d(on)}		P-Ch		10	15		
Turn-On Delay Time		P-Channel	N-Ch		10	15	-	
Diag Time		$V_{DD} = -15 \text{ V}, R_L = 5 \Omega$	P-Ch		20	30		
Rise Time		$I_D \cong -3 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 1 \Omega$	N-Ch		15	25		
Turn-Off Delay Time	t _{d(off)}	N-Channel	P-Ch		25	40	ns	
		V_{DD} = 15 V, R_L = 5 Ω	N-Ch		20	30	_	
Fall Time		$I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 1 \Omega$	P-Ch		30	45		
		I _F = - 1.7 A, dl/dt = 100 A/μs	N-Ch P-Ch		10	15 50	-	
Source-Drain Reverse Recovery Time	t _{rr}	$I_F = 1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$ $I_F = 1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$	N-Ch		25 20	50 40		
		i _F = 1.7 A, αί/αι = 100 A/μS	IN-CII		20	40	<u> </u>	

Notes:

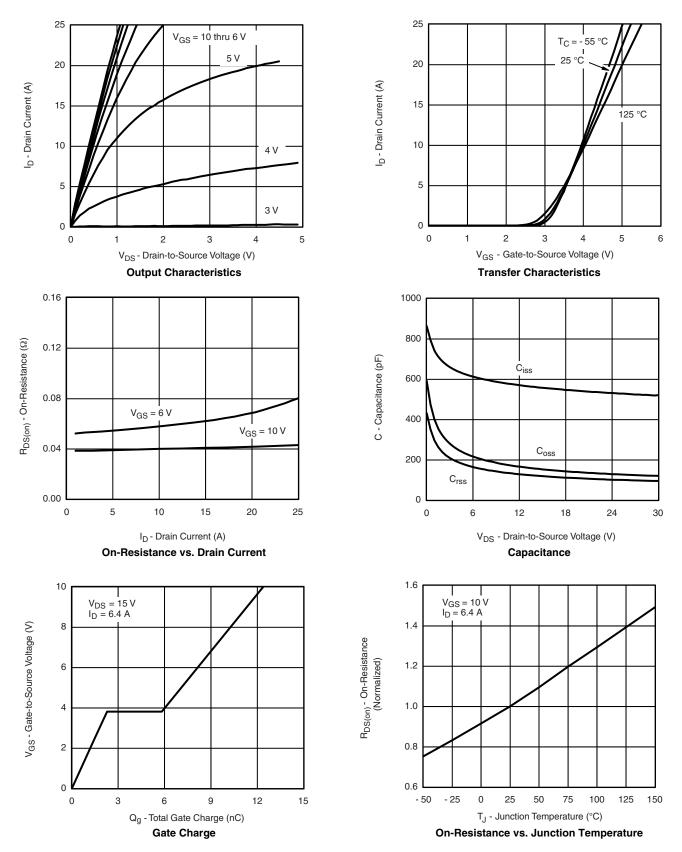
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

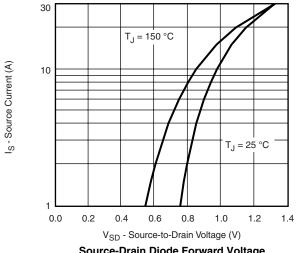


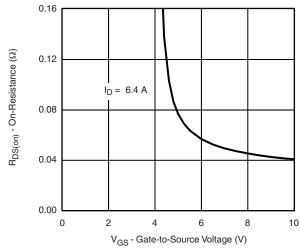


P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



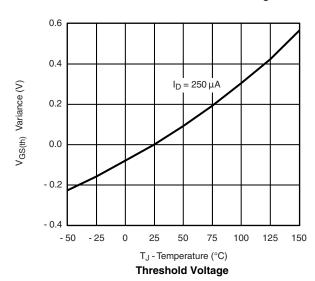
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

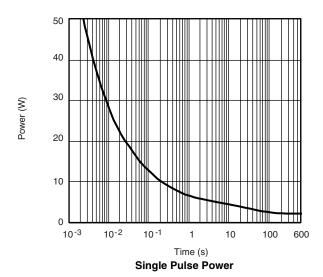


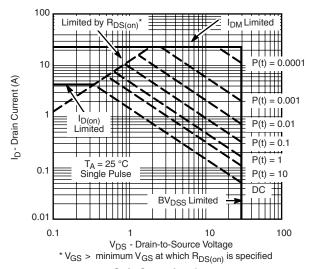


Source-Drain Diode Forward Voltage





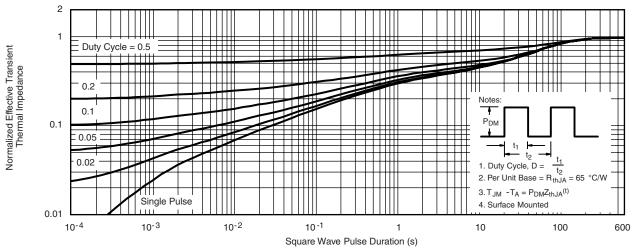




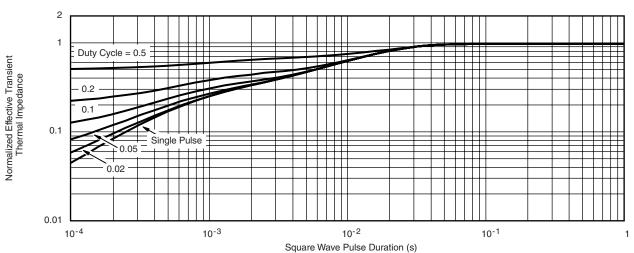
Safe Operating Area



P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



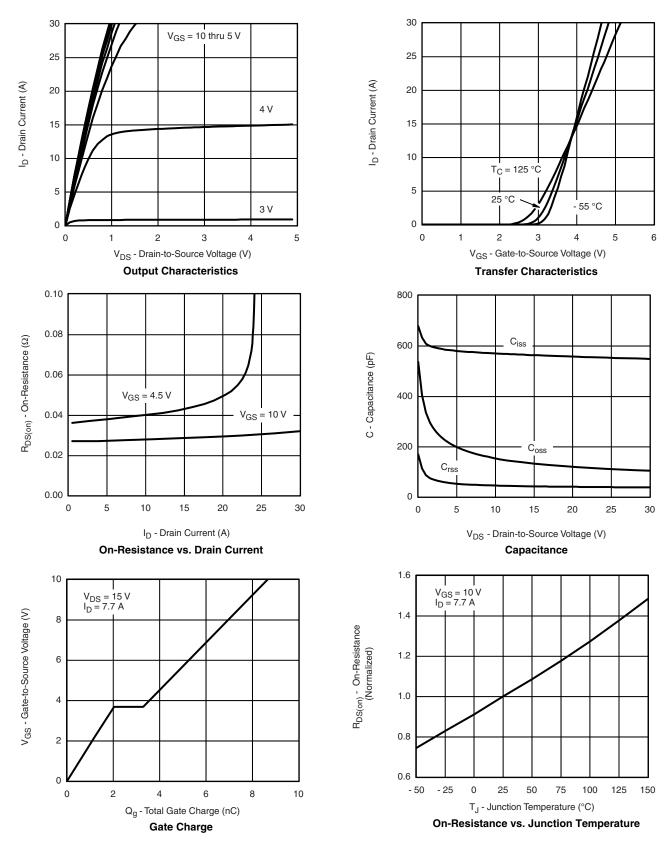
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

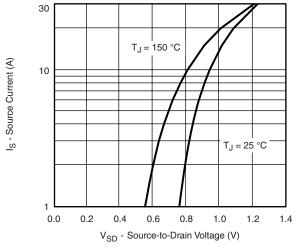


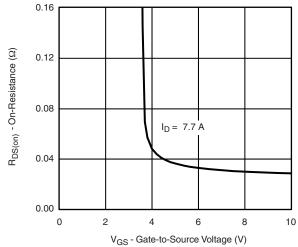
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





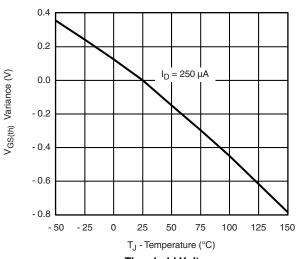
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

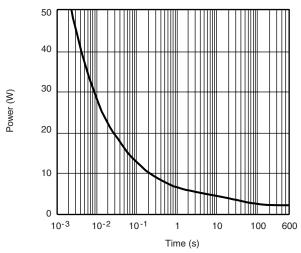




Source-Drain Diode Forward Voltage

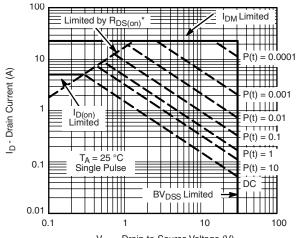






Threshold Voltage

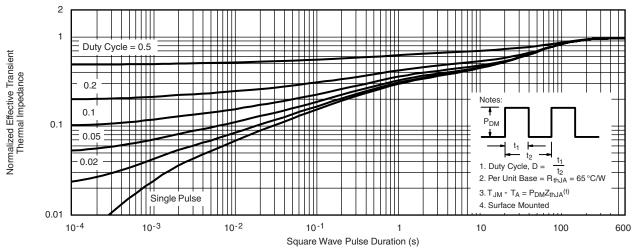
Single Pulse Power



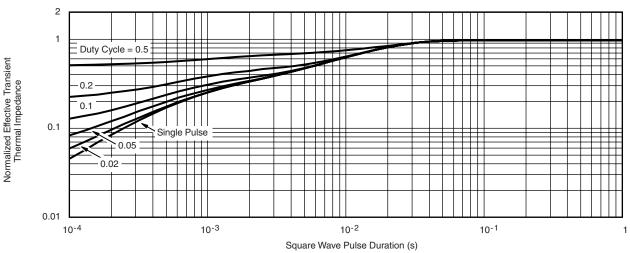
$$\begin{split} &V_{DS}\text{ - Drain-to-Source Voltage (V)}\\ ^*V_{GS}>&&\min W_{GS}\text{ at which }R_{DS(on)}\text{ is specified}\\ &\textbf{Safe Operating Area} \end{split}$$



N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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